

On page 13, lines 12-15, please replace the paragraph with the following:

The TFT array substrate 500 of Fig. 21 is assembled with an organic EL substrate 600 in Fig. 25. Figs. 22, 23, 24 and 25 are cross-sectional views illustrating a process of manufacturing the organic EL substrate 600 according to the second preferred embodiment of the present invention.

In the Claims:

Please delete claim 2 without any disclaimer and a prejudice to and amend claims 1, 3, 6-9 and 11 as follows and add a new claim 25.

1. (Amended) An organic EL device, comprising:

a thin film transistor (TFT) array substrate including a first insulating substrate, a TFT with a conductive interface pad connected thereto and a capacitor formed on the first insulating substrate; and

an organic EL substrate including a second insulating substrate, a transparent electrode, an organic EL layer and a metal electrode,

wherein the conductive interface pad is directly connected to the metal electrode.

3. (Amended) The device of claim 1, wherein the organic EL substrate further includes a protection film that prevents external oxygen and moisture from permeating.

6. (Amended) An organic EL device, comprising:

a thin film transistor (TFT) array substrate including a first insulating substrate, a TFT with a conductive interface pad connected thereto, a capacitor formed on the first insulating substrate and a conductive bump pad formed on the conductive interface pad; and

an organic EL substrate including a second insulating substrate, a transparent electrode, an organic EL layer and a metal electrode,

wherein the conductive bump pad is directly connected to the metal electrode.

7. (Amended) The organic EL device of claim 25, wherein the conductive bonding agent is an anisotropic conductive film (ACF).

8. (Amended) The organic EL device of claim 7, wherein the anisotropic conductive film prevents external oxygen and moisture.

9. (Amended) An organic EL device, comprising:

a thin film transistor (TFT) array substrate including a first insulating substrate, a TFT, a capacitor formed on the first insulating substrate, a conductive interface pad and a conductive bump pad formed on the conductive interface pad; and

an organic EL substrate including a second insulating substrate, a transparent electrode, an organic EL layer and a metal electrode, and a polymer bump,

wherein the conductive bump pad contacts a portion of the metal electrode corresponding to the polymer bump by a conductive bonding agent, and

wherein the TFT is electrically connected to the metal electrode.